

CLIPPEDIMAGE= JP02001143828A

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TITLE: SOCKET FOR LAND GRID ARRAY TYPE PACKAGE

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INVENTOR-INFORMATION:

NAME	COUNTRY
NODA, ATSUTO	N/A

INT-CL_(IPC): H01R024/10; G01R031/26 ; H01R033/76

ABSTRACT:

PROBLEM TO BE SOLVED: To provide a socket which is obtainable of high connecting reliability of a terminal group for a land grid array type package with electrodes on a board and is compatible with trend of thinner, smaller and higher-density semiconductor package.

SOLUTION: The socket 1 for mounting a land grid array type of package 4 to a board 6 comprises a flexible wiring board 30 in which the first group of electrodes 31 being connected with terminal electrodes of the array type of the package 4 are mounted to one side and the second group of electrodes 32 being connected with electrode group on the board 6 are mounted to the other side, a socket body 2 for mounting the flexible wiring board 30, and a cover 3 for pressing and attaching the package 4 toward the socket body 2. Each electrode of the first group of electrodes 31 and each electrode of the second group of electrodes 32 are disposed not to be overlapped with each other in the direction of a thickness the flexible wiring board 30.

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